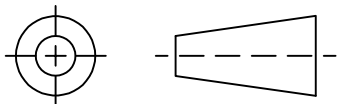


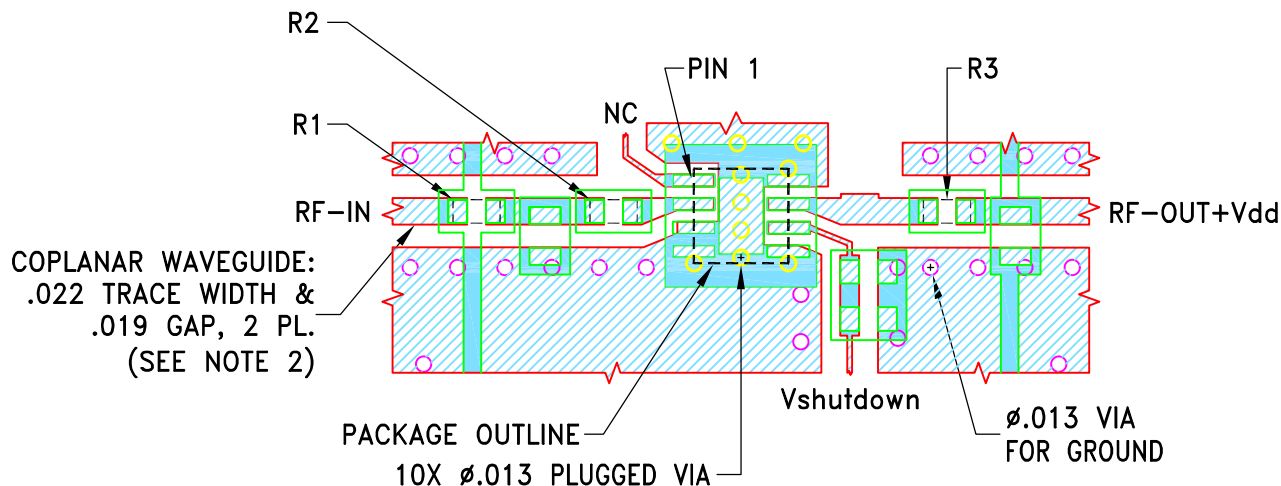
THIRD ANGLE PROJECTION



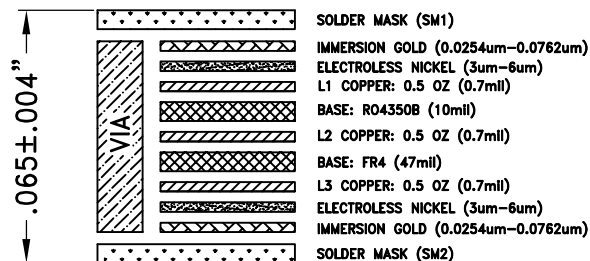
REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	ECO-027827	NEW RELEASE	12/03/25	ITG	IL

SUGGESTED MOUNTING CONFIGURATION FOR MC1631-1 CASE STYLE



3 LAYER STACK-UP DETAIL



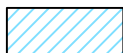
COMPONENT	SIZE
R1-R3	0402

NOTES:

1. PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
2. TRACE WIDTH & GAP ARE SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .010".
COPPER: 1/2 OZ. EACH LAYER. FOR OTHER MATERIALS TRACE WIDTH & GAP MAY NEED TO BE MODIFIED.
3. CHIP COMPONENT FOOT PRINTS SHOWN FOR REFERENCE, FOR COMPONENT VALUES REFER TO TB-TSS-63ULNC+.
4. LAYERS 2 & 3 OF PCB ARE CONTINUOUS GROUND PLANE.
5. UNIT LAND PATTERN WAS OPTIMIZED FOR BETTER PERFORMANCE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN	ITG
TOLERANCES ON:	CHECKED	GF
2 PL DECIMALS ±	APPROVED	IL
3 PL DECIMALS ± .005		
ANGLES ±		
FRACTIONS ±		

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Brooklyn NY 11235

PL, MC1631-1, TB-TSS-63ULNC+

SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-849	OR
FILE:	98PL849	SCALE:	6:1
		SHEET:	1 OF 1